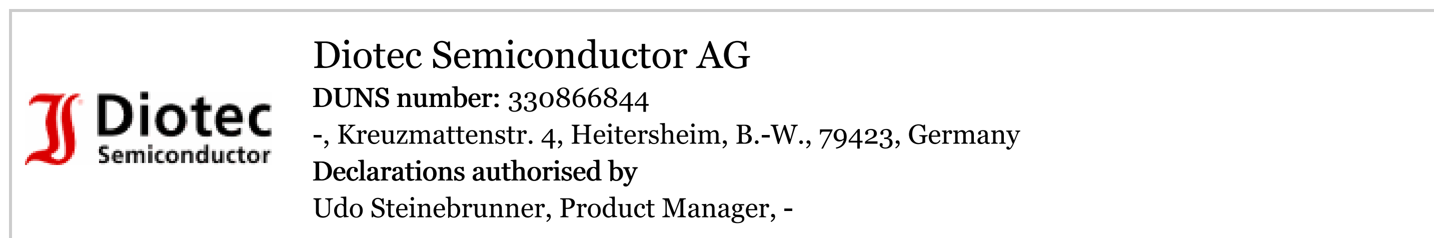
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 05 February 2024, 14:56 GMT



Diotec Semiconductor AG

DUNS number: 330866844
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Declarations authorised by
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved: 05 February 2024 14:55 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	**Material Group**	**Max mass %**	**Substance**	**CAS Number**	**Max mass %**
Chip (die)	Other inorganic materials	1.09%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	74%	Carbon black	1333-86-4	0.7%
			ZINCITE (MINERAL)	1314-13-2	0.8%
			Melamine isocyanurate	37640-57-6	1%
			Boron zinc hydroxide oxide	138265-88-0	3.5%
			Phenol, polymer with formaldehyde	9003-35-4	9%
			Silicon Dioxide	7631-86-9	85%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.15%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.74%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	24.02%	Copper	7440-50-8	0.168%
			SILVER, ELEMENTAL	7440-22-4	1.196%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.636%

Attached parts list

Part number	Part name
SOD-323_PbF_HF_Cu	Diode SMD